Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, May 19, 2012 01:59 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
74ACT244MTCX	74ACT244MTCX	TSSOP-20 (NiPdAu) (G)			INTERNAL PENANG	**0.074**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	**1 - Item(s) does not contain RoHS restricted substances per the definition above**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC
0

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TSSOP-20 (NiPdAu) (G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	1.250	Supplier		Silicon	1.250	7440-21-3	16984
Die Attach	Other Organic Materials	0.136	Supplier		Resin	0.027	54208-63-8	370
			Supplier		Silver	0.109	7440-22-4	1481
Encapsulation	Thermoplastics	40.867	Supplier		Carbon Black	0.409	1333-86-4	5553
			Supplier		Epoxy Resin	8.173	29690-82-2	111057
			Supplier		Silica, vitreous	32.285	60676-86-0	438674
Lead Frame	Copper & its alloys	30.624	Supplier		Copper	29.400	7440-50-8	399475
			Supplier		Magnesium	0.046	7439-95-4	624
			B	Nickel (external applications only)	Nickel	0.979	7440-02-0	13302
			Supplier		Silicon	0.199	7440-21-3	2704
Plating	Precious metals	0.223	Supplier		Gold	0.004	7440-57-5	58
			B	Nickel (external applications only)	Nickel	0.213	7440-02-0	2894
			Supplier		Palladium	0.006	7440-05-3	85
Wire Bond	Precious metals	0.496	Supplier		Gold	0.496	7440-57-5	6739